

ABSTRACT

SEMICONDUCTOR-PROCESSING TEMPORARY-ADHESIVE TAPE

A semiconductor-processing temporary-adhesive tape, comprising: a
5 base; and a temporary-adhesive layer provided on one side of the base, wherein
the base is composed of a multilayer structure, at least one of which is a layer A
containing a cyclic olefin polymer with a proportion of 80% by mass or more, and
separately from the layer A, said multilayer structure has a layer B containing a
linear low-density polyethylene or a high-density polyethylene.
10 {Solution to problem}
(Fig. 1)